Applin No.: 10/032,941 Page 1 of 17 Applicant(s): Harry Hadler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING

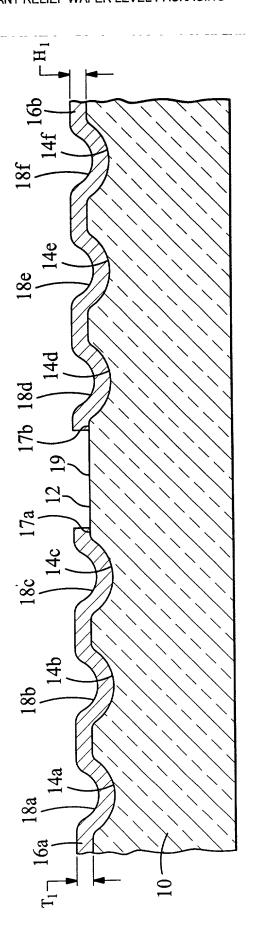
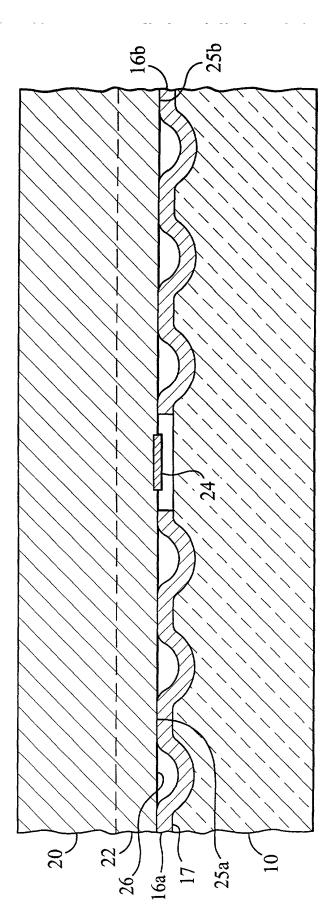


FIG. 1

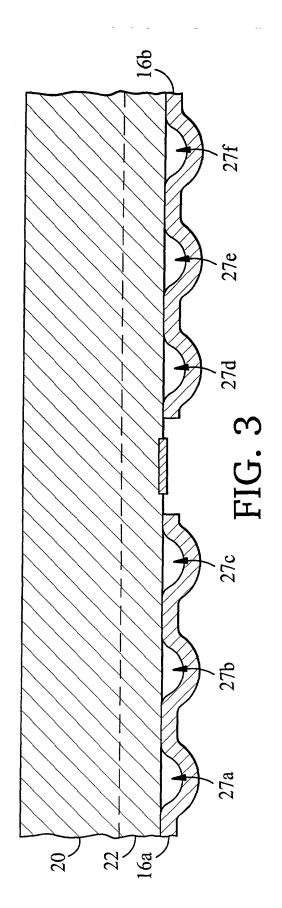
Applin No.: 10/032,941 Pa
Applicant(s): Harry Hedler et al.
CO GLIANT RELIEF WAFER LEVEL PACKAGING

Page 2 of 17



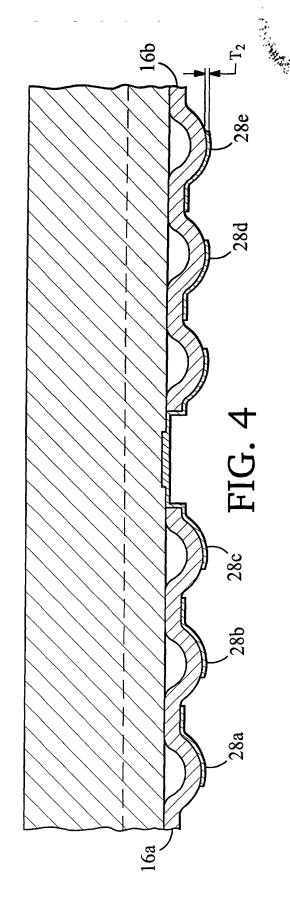
Page 3 of 17

Appln No.: 10/032,941 Pa Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING



The Time the time that the time that the

Control of the contro



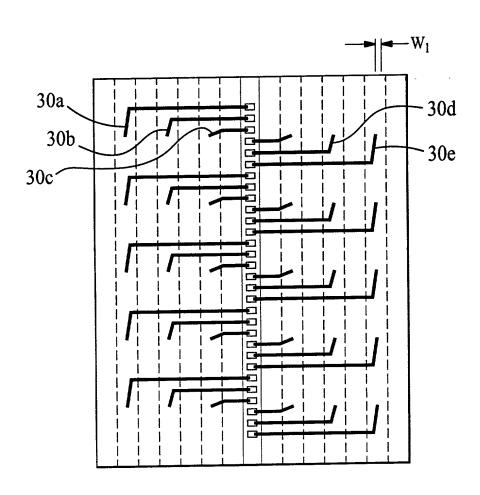
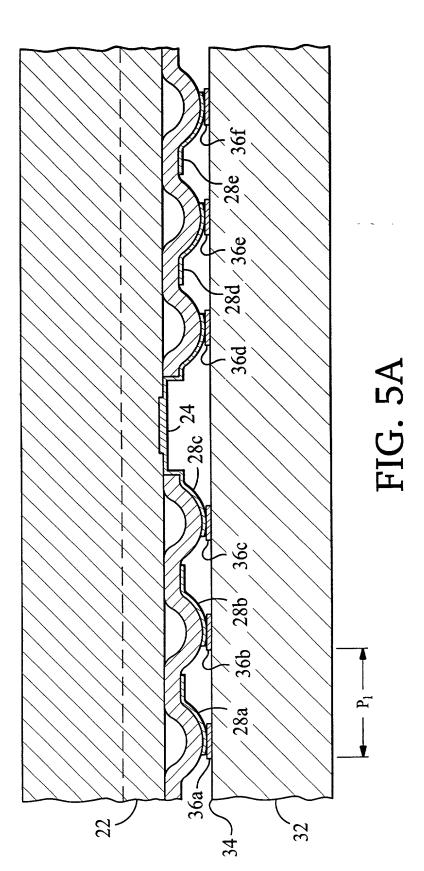


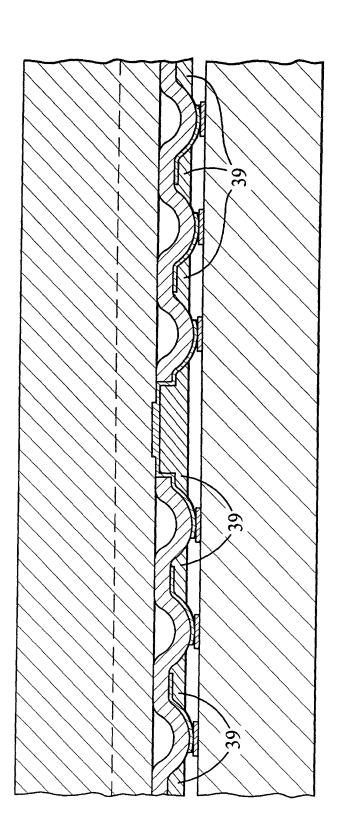
FIG. 4A

Appln No.: 10/032,941 Pa Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING



The state of the s them the control of t

Appln No.: 10/032,941 Pa
Applicant(s): Harry Hedler et al.
CC: 'S' LIANT RELIEF WAFER LEVEL PACKAGING



A The stand them then the stand that the stands of the sta 

Applin No.: 10/032,941 Pa Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING

Page 7 of 17

28b



The North Street Street

Appin No.: 10/032,941 Paralicant(s): Harry Hedier et al.
Compliant RELIEF WAFER LEVEL PACKAGING

FIG. 7

Applin No.: 10/032,941 Pa Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING

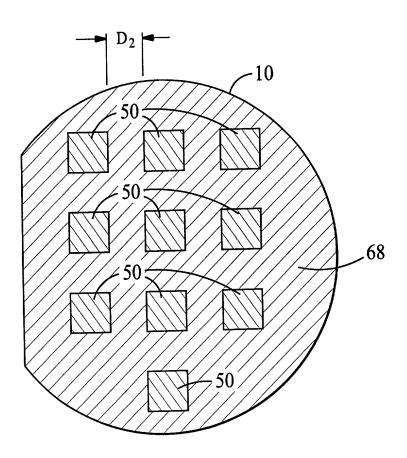


FIG. 7A

The North Street Committee of the Street Street

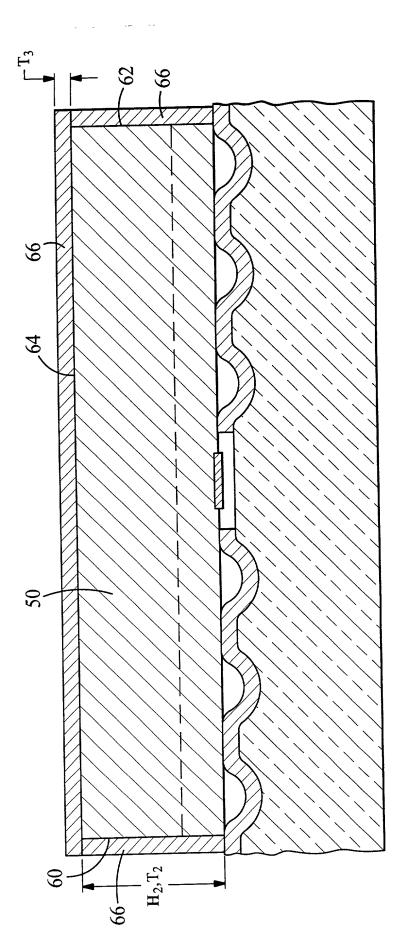


FIG. 8

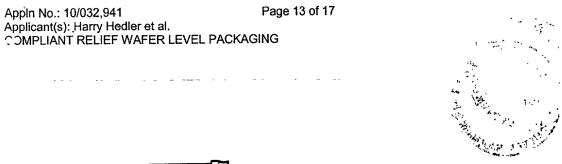
Appln No.: 10/032,941 Page 11 of 17
Applicant(s): Harry Hedler et al.
COMPLIANT RELIEF WAFER LEVEL PACKAGING

50

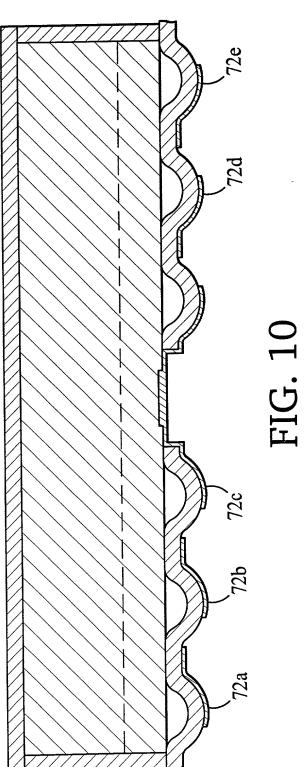
Appln No.: 10/032,941 Pag
Applicant(s): Harry Hedler et al.
CCMPLIANT RELIEF WAFER LEVEL PACKAGING

 $D_2$ -10 .66

FIG. 9A



Page 13 of 17



Hand to the state of the state

Applin No.: 10/032,941 Pag Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING

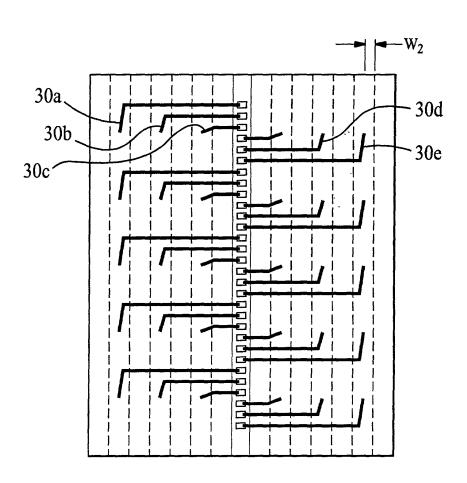


FIG. 10A

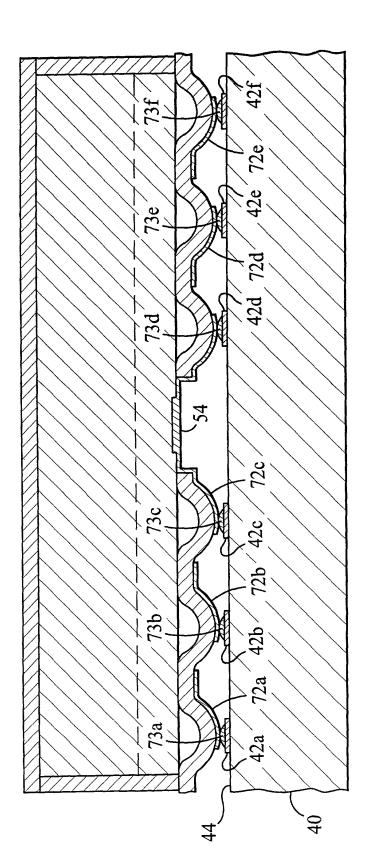
Applin No.: 10/032,941 Pag
Applicant(s): Harry Hedler et al.
COMPLIANT RELIEF WAFER LEVEL PACKAGING

Page 15 of 17



Page 16 of 17

Appln No.: 10/032,941 Pag Applicant(s): Harry Hedler et al. CCMPLIANT RELIEF WAFER LEVEL PACKAGING



ş,

Applin No.: 10/032,941 Pag Applicant(s): Harry Hedler et al. COMPLIANT RELIEF WAFER LEVEL PACKAGING

Page 17 of 17

80